Career Without Limits

Hitch your career with TSMC!

Joining TSMC

TSMC truly believes that talents are the corner stone to reach ambitious goals in future. If you are looking for a world-class organization that is widely recognized by the society and the industry, TSMC is your choice.

Talents we are looking for

Category	Specific areas for reference
Circuit Design Technologies	This area covers the broad scope of circuit design (digital, analog), RF, mini-meter wave, and application-specific IC.
Electronic Device, Process, and Patterning Technologies	This area includes a wide range o novel electronic device structures, and process including Si CMOS, sensors, memory technologies, TCAD, and MEMS.
Properties of Electronic Materials	This area covers the whole range of materials used in current or future manufacturing of nano-scale electronics devices, special focus on chemistry, physics and materials.
Supporting Functions	This area covers Information Technology, Human Resources, Finance, Industrial Engineering, etc.

How to apply

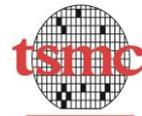To learn the latest openings and apply, please visit our career website:
http://www.tsmc.com/english/careers/jobs.html

Taiwan Semiconductor Manufacturing Company Limited

Hot Job Openings

#	Job Title	Responsibility	Location
1	Advanced Device Engineer	1. Device performance /reliability / process development. 2. Initiate experiment plan, Lot handling, and analysis. 3. Wafer Acceptance Test (WAT) analysis and yield improvement. 4. Task owner for critical issues.	Taiwan (Hsinchu)
2	Advanced Integration Engineer	1.Advanced process & device integration, window characterization. 2. Co-work with device and process module to develop advanced technology. 3. WAT trouble shooting & yield improvement by process optimization and technology transfer. 4. Customer technical interface, NTO and customers handling.	Taiwan (Hsinchu/ Tainan)
3	Advanced Module Engineer (Litho/Etch/CMP/Epi)	1. Advanced module process development and baseline sustaining 2. Process stability/manufacturability improvement for yield and reliability qualification 3. Process/tool transfer to volume manufacturing	Taiwan (Hsinchu/ Tainan)
4	Advanced Lithography Engineer	1. Advanced lithography module process development and baseline sustaining. 2. Process stability/manufacturability improvement for yield and reliability qualification. 3. Process/tool transfer to volume manufacturing.	Taiwan (Hsinchu)
5	Yeild Engineer	1. Advanced technology development. 2. In-line inspection and defect detection, root cause analysis. Work with integration and modules to drive defect reduction. 3. In-line inspection recipe and methodology development.	Taiwan (Hsinchu)
6	Optical Proximity Correction (OPC) Engineer	1. Recipe development for Optical proximity correction (OPC) recipes and multiple patterning decomposition recipes. 2. Optical proximity correction (OPC) taped-out layer sponsors. 3. Resolution enhancement technology development.	Taiwan (Hsinchu)

Hot Job Openings

#	Job Title	Responsibility	Location
7	Extreme Ultraviolet Lithography (EUV) Mask Engineer	1. Technology development of Mask inspection. 2. Verify the Extreme ultraviolet lithography (EUV) mask inspection criteria. 3. Reach and development E-beam inspection tool for mask defect detection. 4. Optical inspection tool verification.	Taiwan (Hsinchu)
8	Mechanical Simulation Expert	1. Provide consultation of mechanical modeling, simulation and insight of physics for semiconductor industry process and materials. 2. Design innovative structure or new flow to enhance device performance, yield improvement, and metrology development.	Taiwan (Hsinchu)
9	SPICE Modeling Engineer	1. Extract SPICE model parameters and device characterization. 2. Customer support. 3. Model document creation.	Taiwan (Hsinchu)
10	SRAM Device Engineer	1. N10 SRAM device optimization, development. 2. Design / Maintenance for SRAM Bit-Cell IP. 3. Quality Enhancement for SRAM IP Portfolio. 4. N10 SRAM device TCAD simulation.	Taiwan (Hsinchu)
11	MEMS Engineer	1. Development on MEMS technology (Physical sensor, Gyroscope, etc.) 2. Advanced process & device integration	Taiwan (Hsinchu)
12	CMOS Image Sensor (CIS) Engineer	Development on CIS technology and device design/simulation	Taiwan (Hsinchu)
13	Power IC Engineer	1. Cross team collaboration to enable new technology/process development for power IC 2. Power device design, characterization and reliability 3. Cross team collaboration for design support documents, DRM,DRC,SPICE,LVS,PDK... 4. Customer design support to enable new business	Taiwan (Hsinchu)